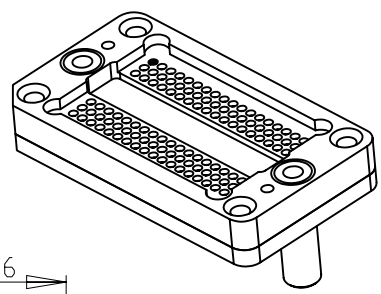


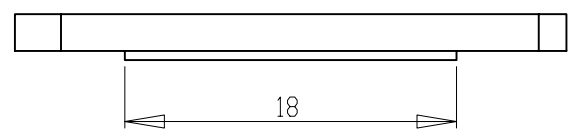
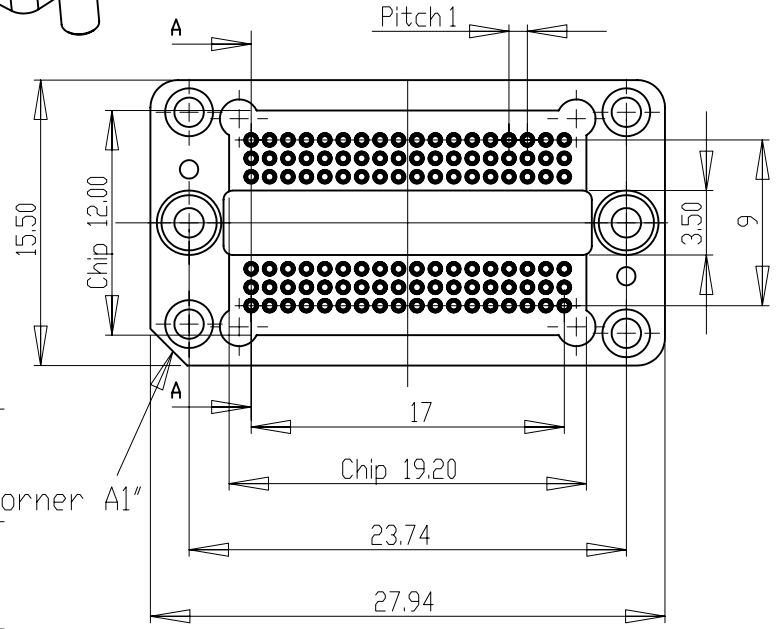
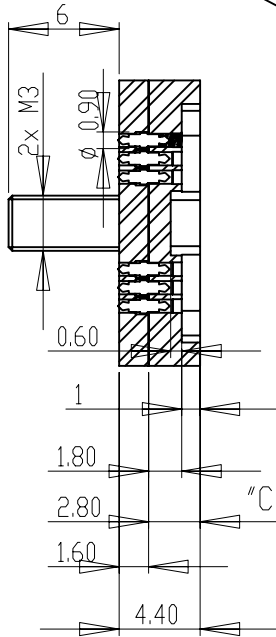
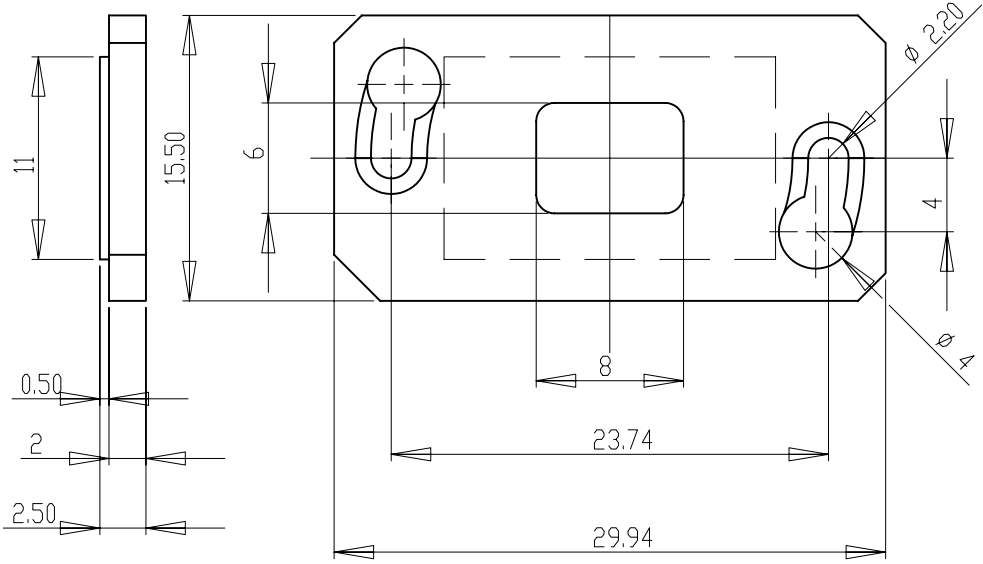
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	03/01/07	H.N.
B	CHANGED LID SIDE & CAVITY DEPTH	05/04/07	K.B.
C	UPDATED DRAWING PER CUST SPEC	05/11/07	H.N.
D	ADDED PIN SPRING DETAIL	05/16/07	H.N.

SKT2870



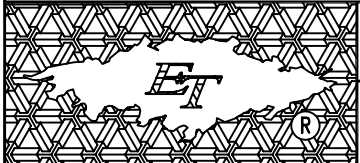
Socket
Material: TG 200

Retention frame
Material: Epoxy FR4



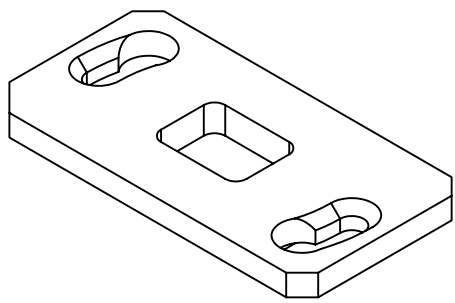
PACKAGE SPECIFICATIONS	
PIN COUNT	= 108
LEAD PITCH	= 1.00mm
GRID SIZE	= 10X18
PACKAGE SIZE	= 12.00X19.20mm
IC BALL DIA	= 0.70mm MAX
BALL HEIGHT	= 0.50mm MAX.

ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F
Santa Clara, Ca 95051
TEL:(408)982-0660
FAX:(408)982-0664



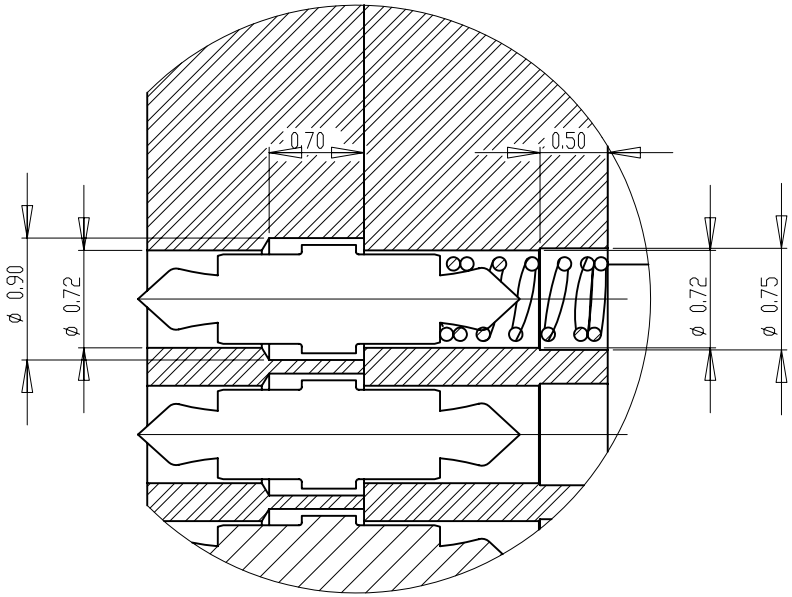
UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
SURFACE FINISH:
GENERAL TOLERANCES: ±0.10
LINEAR:
ANGULAR:

SHEET: 1 OF 2	DATE: 03/01/07	REVISION: D	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: S-MBG-18-108-SC	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: BPP-108-3BG10X18-90	

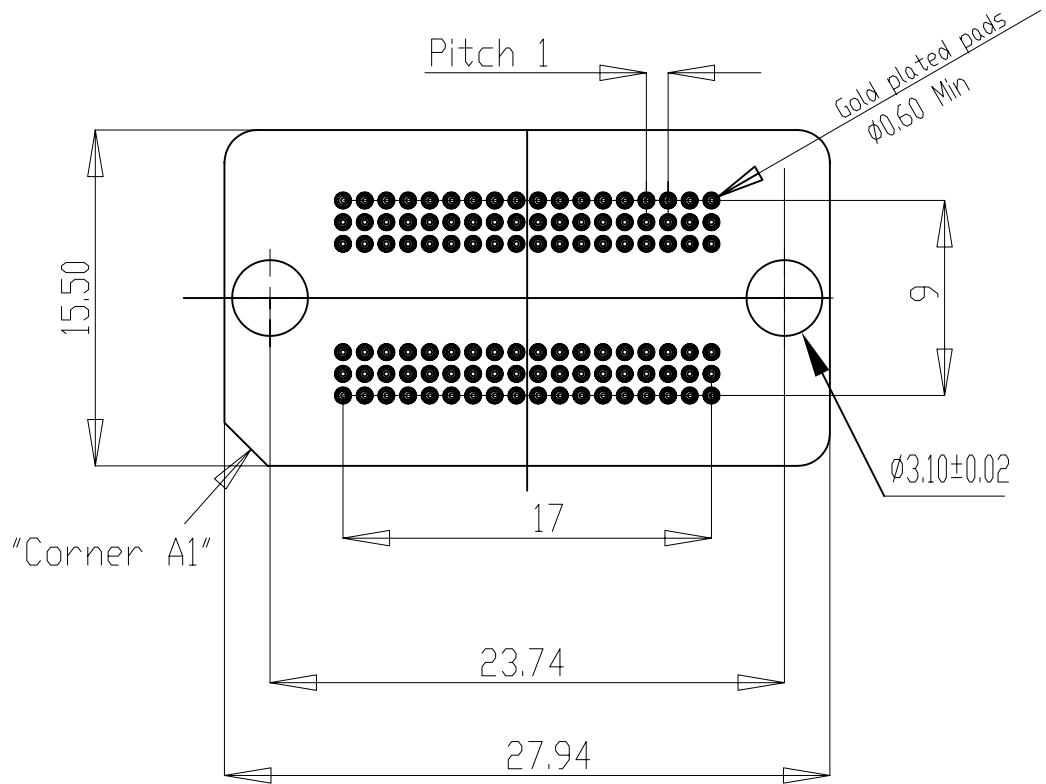
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	03/01/07	H.N.
B	CHANGED LID SIDE & CAVITY DEPTH	05/04/07	K.B.
C	UPDATED DRAWING PER CUST SPEC	05/11/07	H.N.
D	ADDED PIN SPRING DETAIL	05/16/07	H.N.

SKT2870

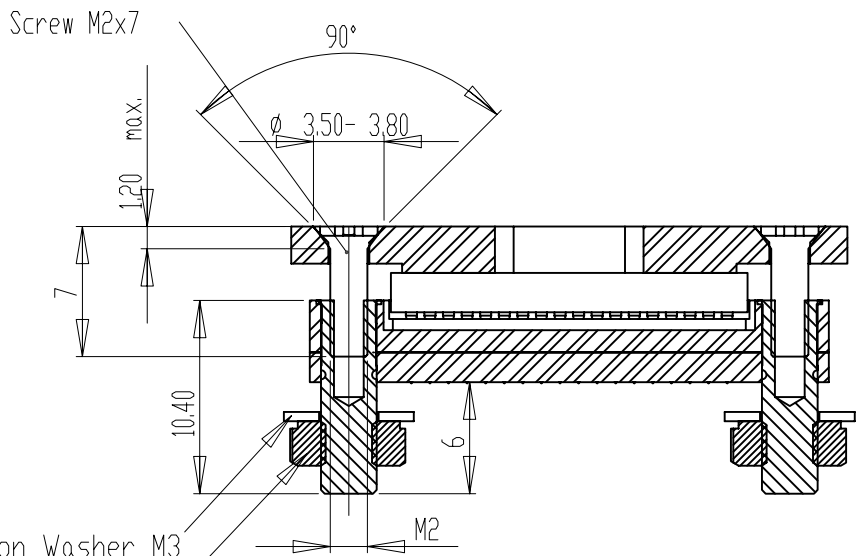
PCB LAYOUT (TOP VIEW)



PIN DETAIL

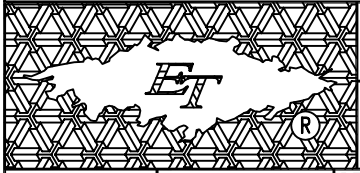


"Corner A1"



SECTION A-A

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SHEET: 2 OF 2	DATE: 03/01/07	REVISION: D	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.		
Scale N/A		DO NOT SCALE DRAWING	
			DESCRIPTION: BPP-108-3BG10X18-90